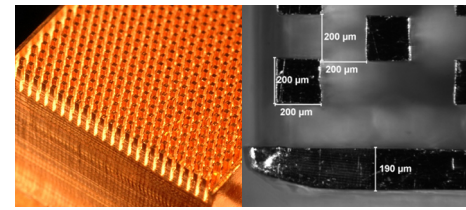




# ICOMM/4M 2010

April 5-9, 2010

Madison, WI USA



## The 5<sup>th</sup> International Conference on MicroManufacturing

**ICOMM/4M 2010** focuses on the processes, equipment, and systems for fabricating miniature parts with micro-scale features.



The Lowell Center

Many fields, including medical, aerospace, military/defense, optics, automotive, consumer products, and communications, have been increasingly demanding miniature devices and components with complex micro-scale features made from a wide selection of materials. Some current applications of miniature parts - with dimensions ranging from a few micrometers to tens of millimeters - include miniature motors and turbines, micro-satellites, implantable medical devices, minimally invasive surgery equipment, micro robots, and miniature molds and dies. It is expected that miniature parts will be increasingly demanded in the future.



### Papers are sought to address theoretical and applied research issues related to manufacture, assembly, and metrology for components and systems with micro-scale features.

Topics may include, but are not limited to, mechanics and dynamics of process behavior at the microscale; the miniaturization of machines and equipment as well as associated issues such as tooling, fixturing, positioning, motion generation, sensors systems, and control; the microfactory paradigm; new concepts and methods for micro-scale metrology; materials handling, joining, and assembly at the micro-scale; multi-scale modeling and simulation; design for micro-scale manufacturing; and materials-

related issues at the micro-scale. A broad range of processes will be considered including machining, forming, EDM and ECM, laser-based processing, casting and molding, and others.

Papers are also sought that describe interesting applications of both current and emerging micromanufacturing methods and equipment, including those that bridge the nano- and macro- worlds. All papers must be technical in nature and include original work. **Copyrights remain with the authors. Abstracts due on 30 October 2009. Final Manuscripts due on 19 February 2010.**

We look forward to seeing you on the shore of Lake Mendota.

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